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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Tai-Peng Lee; Chuck Jang
Assignee: Mosel Vitelic, Inc.
Title: Reduces Thickness Variation In A Material Layer Deposited In Narrow
and Wide Integrated Circuit Trenches
Serial No.: 10/033,114 Filing Date: October 22, 2001
Examiner: Garcia, Joanne A. Group Art Unit: 2823
Docket No.: M-11912 US

San Jose, California
December 10, 2003

COMMISSIONER FOR PATENTS
P.O. BOX 1450
ALEXANDRIA, VA 22313-1450

RESPONSE TO OFFICE COMMUNICATION

Dear Sir:

In response to the Office Communication having a mailing date of Dec. 3, 2003,
please accept the below revised, version of the annotated claims for entry in the record of the
above-identified patent application. This supplements the response of 08-18-03.

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